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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	1694
Number of Logic Elements/Cells	33880
Total RAM Bits	1369728
Number of I/O	500
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2s30f672c3

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

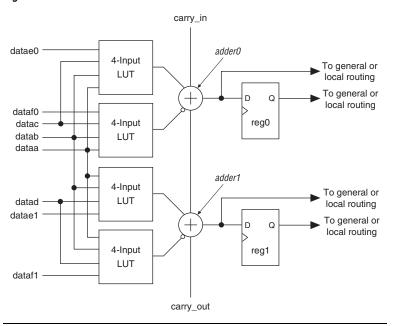


Figure 2-11. ALM in Arithmetic Mode

While operating in arithmetic mode, the ALM can support simultaneous use of the adder's carry output along with combinational logic outputs. In this operation, the adder output is ignored. This usage of the adder with the combinational logic output provides resource savings of up to 50% for functions that can use this ability. An example of such functionality is a conditional operation, such as the one shown in Figure 2–12. The equation for this example is:

$$R = (X < Y) ? Y : X$$

To implement this function, the adder is used to subtract 'Y' from 'X.' If 'X' is less than 'Y,' the carry_out signal is '1.' The carry_out signal is fed to an adder where it drives out to the LAB local interconnect. It then feeds to the LAB-wide syncload signal. When asserted, syncload selects the syncdata input. In this case, the data 'Y' drives the syncdata inputs to the registers. If 'X' is greater than or equal to 'Y,' the syncload signal is de-asserted and 'X' drives the data port of the registers.

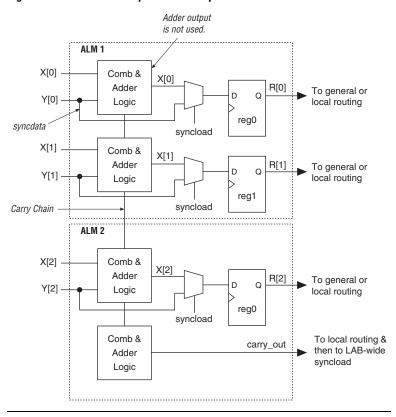


Figure 2-12. Conditional Operation Example

The arithmetic mode also offers clock enable, counter enable, synchronous up/down control, add/subtract control, synchronous clear, synchronous load. The LAB local interconnect data inputs generate the clock enable, counter enable, synchronous up/down and add/subtract control signals. These control signals are good candidates for the inputs that are shared between the four LUTs in the ALM. The synchronous clear and synchronous load options are LAB-wide signals that affect all registers in the LAB. The Quartus II software automatically places any registers that are not used by the counter into other LABs.

Carry Chain

The carry chain provides a fast carry function between the dedicated adders in arithmetic or shared arithmetic mode. Carry chains can begin in either the first ALM or the fifth ALM in an LAB. The final carry-out signal is routed to an ALM, where it is fed to local, row, or column interconnects.

LABs on right and left sides for easy access to horizontal I/O pins M-RAM M-RAM Block Block M-RAM M-RAM Block Block M-RAM M-RAM Block Block DSP DSP M4K M512 LABs **Blocks** Blocks **Blocks** Blocks

Figure 2–24. EP2S130 Device with M-RAM Interface Locations Note (1)

M-RAM blocks interface to

Note to Figure 2–24:

(1) The device shown is an EP2S130 device. The number and position of M-RAM blocks varies in other devices.

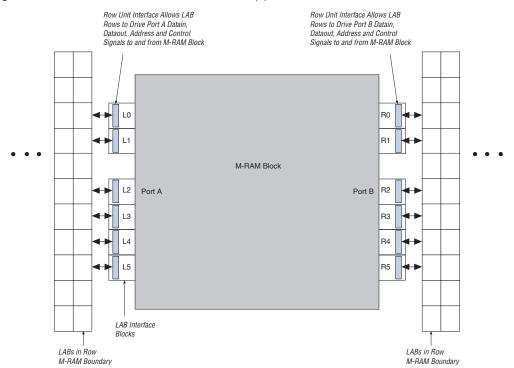


Figure 2–25. M-RAM Block LAB Row Interface Note (1)

Note to Figure 2–25:

(1) Only R24 and C16 interconnects cross the M-RAM block boundaries.

IOE clocks have row and column block regions that are clocked by eight I/O clock signals chosen from the 24 quadrant clock resources. Figures 2–35 and 2–36 show the quadrant relationship to the I/O clock regions.

IO_CLKA[7:0] IO_CLKB[7:0] 8 I/O Clock Regions 24 Clocks in 24 Clocks in the Quadrant the Quadrant IO_CLKH[7:0] IO_CLKC[7:0] **∦**8 IO_CLKG[7:0] IO_CLKD[7:0] 24 Clocks in 24 Clocks in the Quadrant the Quadrant 8 8 IO_CLKF[7:0] IO_CLKE[7:0]

Figure 2-35. EP2S15 & EP2S30 Device I/O Clock Groups



When using the global or regional clock control blocks in Stratix II devices to select between multiple clocks or to enable and disable clock networks, be aware of possible narrow pulses or glitches when switching from one clock signal to another. A glitch or runt pulse has a width that is less than the width of the highest frequency input clock signal. To prevent logic errors within the FPGA, Altera recommends that you build circuits that filter out glitches and runt pulses.

Figures 2–37 through 2–39 show the clock control block for the global clock, regional clock, and PLL external clock output, respectively.

Pins PLL Counter Outputs CLKn Internal Pin Logic Static Clock Select (2) This multiplexer supports User-Controllable Dynamic Switching Enable/ Disable Internal Logic **GCLK**

Figure 2-37. Global Clock Control Blocks

Notes to Figure 2-37:

- These clock select signals can be dynamically controlled through internal logic when the device is operating in user mode.
- (2) These clock select signals can only be set through a configuration file (.sof or .pof) and cannot be dynamically controlled during user mode operation.

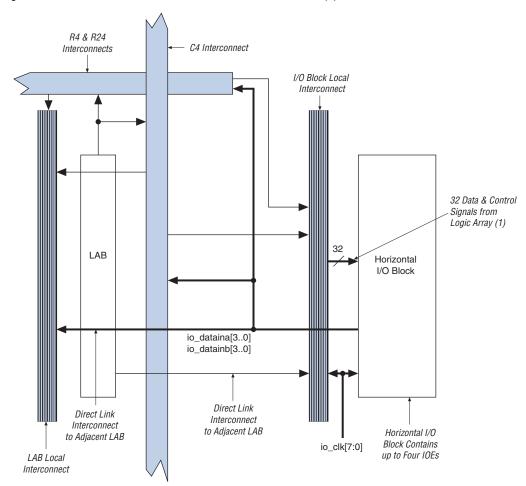


Figure 2–47. Row I/O Block Connection to the Interconnect Note (1)

Note to Figure 2–47:

(1) The 32 data and control signals consist of eight data out lines: four lines each for DDR applications io_dataouta[3..0] and io_dataoutb[3..0], four output enables io_oe[3..0], four input clock enables io_ce_in[3..0], four output clock enables io_ce_out[3..0], four clocks io_clk[3..0], four asynchronous clear and preset signals io_aclr/apreset[3..0], and four synchronous clear and preset signals io_sclr/spreset[3..0].

Table 2–23. E	P2S60 Differei	ntial Chann	els N	ote (1)							
Dankago	Transmitter/	Total		Center F	ast PLLs	1	Corner Fast PLLs (4)				
Package	Receiver	Channels	PLL 1	PLL 2	PLL 3	PLL 4	PLL 7	PLL 8	PLL 9	PLL 10	
484-pin	Transmitter	38 (2)	10	9	9	10	10	9	9	10	
FineLine BGA		(3)	19	19	19	19	-	-	-	-	
	Receiver	42 (2)	11	10	10	11	11	10	10	11	
		(3)	21	21	21	21	-	-	-	-	
672-pin	Transmitter	58 (2)	16	13	13	16	16	13	13	16	
FineLine BGA		(3)	29	29	29	29	-	-	-	-	
	Receiver	62 (2)	17	14	14	17	17	14	14	17	
		(3)	31	31	31	31	-	-	-	-	
1,020-pin	Transmitter	84 (2)	21	21	21	21	21	21	21	21	
FineLine BGA		(3)	42	42	42	42	-	-	-	-	
	Receiver	84 (2)	21	21	21	21	21	21	21	21	
		(3)	42	42	42	42	-	-	-	-	

Table 2–24. EP2S90 Differential Channels Note (1)											
Dookogo	Transmitter/	Total		Center Fast PLLs				Corner Fast PLLs (4)			
Package	Receiver	Channels	PLL 1	PLL 2	PLL 3	PLL 4	PLL 7	PLL 8	PLL 9	PLL 10	
484-pin Hybrid	Transmitter	38 (2)	10	9	9	10	-	-	-	-	
FineLine BGA		(3)	19	19	19	19	-	-	-	-	
	Receiver	42 (2)	11	10	10	11	-	-	-	-	
		(3)	21	21	21	21	-	-	-	-	
780-pin	Transmitter	64 (2)	16	16	16	16	-	-	-		
FineLine BGA		(3)	32	32	32	32	-	-	-	-	
	Receiver	68 <i>(2)</i>	17	17	17	17	-	-	-	-	
		(3)	34	34	34	34	-	-	-		
1,020-pin	Transmitter	90 (2)	23	22	22	23	23	22	22	23	
FineLine BGA		(3)	45	45	45	45	-	-	-	-	
	Receiver	94 (2)	23	24	24	23	23	24	24	23	
		(3)	46	46	46	46	-	-	-	-	
1,508-pin	Transmitter	118 (2)	30	29	29	30	30	29	29	30	
FineLine BGA		(3)	59	59	59	59	-	-	-	-	
	Receiver	118 (2)	30	29	29	30	30	29	29	30	
		(3)	59	59	59	59	-	-	-	-	

Operating Modes

The Stratix II architecture uses SRAM configuration elements that require configuration data to be loaded each time the circuit powers up. The process of physically loading the SRAM data into the device is called configuration. During initialization, which occurs immediately after configuration, the device resets registers, enables I/O pins, and begins to operate as a logic device. The I/O pins are tri-stated during power-up, and before and during configuration. Together, the configuration and initialization processes are called command mode. Normal device operation is called user mode.

SRAM configuration elements allow Stratix II devices to be reconfigured in-circuit by loading new configuration data into the device. With real-time reconfiguration, the device is forced into command mode with a device pin. The configuration process loads different configuration data, reinitializes the device, and resumes user-mode operation. You can perform in-field upgrades by distributing new configuration files either within the system or remotely.

PORSEL is a dedicated input pin used to select POR delay times of 12 ms or 100 ms during power-up. When the PORSEL pin is connected to ground, the POR time is 100 ms; when the PORSEL pin is connected to $V_{\rm CC}$, the POR time is 12 ms.

The nio pullup pin is a dedicated input that chooses whether the internal pull-ups on the user I/O pins and dual-purpose configuration I/O pins (ncso, Asdo, data [7..0], nws, nrs, rdynbsy, ncs, cs, runlu, pgm [2..0], clkusr, init_done, dev_oe, dev_clr) are on or off before and during configuration. A logic high (1.5, 1.8, 2.5, 3.3 V) turns off the weak internal pull-ups, while a logic low turns them on.

Stratix II devices also offer a new power supply, V_{CCPD} , which must be connected to 3.3 V in order to power the 3.3-V/2.5-V buffer available on the configuration input pins and JTAG pins. V_{CCPD} applies to all the JTAG input pins (TCK, TMS, TDI, and TRST) and the configuration input pins when VCCSEL is connected to ground. See Table 3–4 for more information on the pins affected by VCCSEL.

The VCCSEL pin allows the V_{CCIO} setting (of the banks where the configuration inputs reside) to be independent of the voltage required by the configuration inputs. Therefore, when selecting the V_{CCIO} , the V_{IL} and V_{IH} levels driven to the configuration inputs do not have to be a concern.

Table 3–5. Stratix II Configuration Features (Part 2 of 2)							
Configuration Scheme	Configuration Method	Design Security	Decompression	Remote System Upgrade			
PPA	MAX II device or microprocessor and flash device			✓			
JTAG	Download cable (4)						
	MAX II device or microprocessor and flash device						

Notes for Table 3–5:

- (1) In these modes, the host system must send a DCLK that is $4\times$ the data rate.
- (2) The enhanced configuration device decompression feature is available, while the Stratix II decompression feature is not available.
- (3) Only remote update mode is supported when using the AS configuration scheme. Local update mode is not supported.
- (4) The supported download cables include the Altera USB Blaster universal serial bus (USB) port download cable, MasterBlaster serial/USB communications cable, ByteBlaster II parallel port download cable, and the ByteBlasterMV parallel port download cable.



See the *Configuring Stratix II & Stratix II GX Devices* chapter in volume 2 of the *Stratix II Device Handbook* or the *Stratix II GX Device Handbook* for more information about configuration schemes in Stratix II and Stratix II GX devices.

Device Security Using Configuration Bitstream Encryption

Stratix II FPGAs are the industry's first FPGAs with the ability to decrypt a configuration bitstream using the Advanced Encryption Standard (AES) algorithm. When using the design security feature, a 128-bit security key is stored in the Stratix II FPGA. To successfully configure a Stratix II FPGA that has the design security feature enabled, it must be configured with a configuration file that was encrypted using the same 128-bit security key. The security key can be stored in non-volatile memory inside the Stratix II device. This non-volatile memory does not require any external devices, such as a battery back-up, for storage.

error status information. This dedicated remote system upgrade circuitry avoids system downtime and is the critical component for successful remote system upgrades.

RSC is supported in the following Stratix II configuration schemes: FPP, AS, PS, and PPA. RSC can also be implemented in conjunction with advanced Stratix II features such as real-time decompression of configuration data and design security using AES for secure and efficient field upgrades.



See the *Remote System Upgrades With Stratix II & Stratix II GX Devices* chapter in volume 2 of the *Stratix II Device Handbook* or the *Stratix II GX Device Handbook* for more information about remote configuration in Stratix II devices.

Configuring Stratix II FPGAs with JRunner

JRunner is a software driver that configures Altera FPGAs, including Stratix II FPGAs, through the ByteBlaster II or ByteBlasterMV cables in JTAG mode. The programming input file supported is in Raw Binary File (.rbf) format. JRunner also requires a Chain Description File (.cdf) generated by the Quartus II software. JRunner is targeted for embedded JTAG configuration. The source code is developed for the Windows NT operating system (OS), but can be customized to run on other platforms.



For more information on the JRunner software driver, see the *JRunner Software Driver: An Embedded Solution to the JTAG Configuration White Paper* and the source files on the Altera web site **(www.altera.com)**.

Programming Serial Configuration Devices with SRunner

A serial configuration device can be programmed in-system by an external microprocessor using SRunner. SRunner is a software driver developed for embedded serial configuration device programming that can be easily customized to fit in different embedded systems. SRunner is able to read a .rpd file (Raw Programming Data) and write to the serial configuration devices. The serial configuration device programming time using SRunner is comparable to the programming time when using the Quartus II software.



For more information about SRunner, see the *SRunner: An Embedded Solution for EPCS Programming* White Paper and the source code on the Altera web site at **www.altera.com**.



For more information on programming serial configuration devices, see the Serial Configuration Devices (EPCS1 & EPCS4) Data Sheet in the *Configuration Handbook*.

Cumbal	Dovomatav	-3 Speed Grade <i>(1)</i>			peed e <i>(2)</i>		peed ide	-5 S Gra	peed ide	Unit	
Symbol	Parameter	Min (3)	Max	Min (3)	Max	Min (4)	Max	Min (3)	Max	Unit	
t _{SU}	Input, pipeline, and output register setup time before clock	50		52		57 57		67		ps	
t _H	Input, pipeline, and output register hold time after clock	180		189		206 206		241		ps	
t _{co}	Input, pipeline, and output register clock-to-output delay	0	0	0	0	0	0	0	0	ps	
tinreg2PIPE9	Input register to DSP block pipeline register in 9 × 9-bit mode	1,312	2,030	1,312	2,030	1,250 1,312	2,334	1,312	2,720	ps	
t _{INREG2PIPE18}	Input register to DSP block pipeline register in 18 × 18-bit mode	1,302	2,010	1,302	2,110	1,240 1,302	2,311	1,302	2,693	ps	
tinreg2PIPE36	Input register to DSP block pipeline register in 36 × 36-bit mode	1,302	2,010	1,302	2,110	1,240 1,302	2,311	1,302	2,693	ps	
t _{PIPE2OUTREG2ADD}	DSP block pipeline register to output register delay in two- multipliers adder mode	924	1,450	924	1,522	880 924	1,667	924	1,943	ps	
t _{PIPE2OUTREG4ADD}	DSP block pipeline register to output register delay in four- multipliers adder mode	1,134	1,850	1,134	1,942	1,080 1,134	2,127	1,134	2,479	ps	
t _{PD9}	Combinational input to output delay for 9×9	2,100	2,880	2,100	3,024	2,000 2,100	3,312	2,100	3,859	ps	
t _{PD18}	Combinational input to output delay for 18 × 18	2,110	2,990	2,110	3,139	2,010 2,110	3,438	2,110	4,006	ps	
t _{PD36}	Combinational input to output delay for 36 × 36	2,939	4,450	2,939	4,672	2,800 2,939	5,117	2,939	5,962	ps	
t _{CLR}	Minimum clear pulse width	2,212		2,322		2,543 2,543		2,964		ps	

Table 5-70. Str	atix II IOE Progra	mmable De	elay on H	Row Pin:	s No	ote (1)				
		Available	Minimum Timing (2)		-3 Speed Grade (3)		-4 Speed Grade		-5 Speed Grade	
Parameter	Paths Affected	Settings	Min Offset (ps)	Max Offset (ps)	Min Offset (ps)	Max Offset (ps)	Min Offset (ps)	Max Offset (ps)	Min Offset (ps)	Max Offset (ps)
Input delay from pin to internal cells	Pad to I/O dataout to logic array	8	0	1,697 1,782	0	2,876 3,020	0	3,308	0	3,853
Input delay from pin to input register	Pad to I/O input register	64	0	1,956 2,054	0	3,270 3,434	0	3,761	0	4,381
Delay from output register to output pin	I/O output register to pad	2	0	316 332	0 0	525 525	0	575	0	670
Output enable pin delay	t_{XZ}, t_{ZX}	2	0	305 320	0 0	507 507	0	556	0	647

Notes to Table 5–70:

- (1) The incremental values for the settings are generally linear. For the exact delay associated with each setting, use the latest version of the Quartus II software.
- (2) The first number is the minimum timing parameter for industrial devices. The second number is the minimum timing parameter for commercial devices.
- (3) The first number applies to -3 speed grade EP2S15, EP2S30, EP2S60, and EP2S90 devices. The second number applies to -3 speed grade EP2S130 and EP2S180 devices.

Default Capacitive Loading of Different I/O Standards

See Table 5–71 for default capacitive loading of different I/O standards.

Table 5–71. Default Loading of Different I/O Standards for Stratix II (Part 1 of 2)						
I/O Standard	Capacitive Load	Unit				
LVTTL	0	pF				
LVCMOS	0	pF				
2.5 V	0	pF				
1.8 V	0	pF				
1.5 V	0	pF				
PCI	10	pF				
PCI-X	10	pF				
SSTL-2 Class I	0	pF				

I/O Delays

See Tables 5–72 through 5–76 for I/O delays.

Table 5–72. I/O Delay Parameters						
Symbol	Parameter					
t _{DIP}	Delay from I/O datain to output pad					
t _{OP}	Delay from I/O output register to output pad					
t _{PCOUT}	Delay from input pad to I/O dataout to core					
t _{P1}	Delay from input pad to I/O input register					

		Minimu	m Timing	-3 Speed	-3 Speed	-4 Speed	-5 Speed		
I/O Standard	Parameter	Industrial	Commercial	Grade (2)	Grade (3)	Grade	Grade	Unit	
LVTTL	t _{PI}	674	707	1223	1282	1405	1637	ps	
	t _{PCOUT}	408	428	787	825	904	1054	ps	
2.5 V	t _{PI}	684	717	1210	1269	1390	1619	ps	
	t _{PCOUT}	418	438	774	812	889	1036	ps	
1.8 V	t _{PI}	747	783	1366	1433	1570	1829	ps	
	t _{PCOUT}	481	504	930	976	1069	1246	ps	
1.5 V	t _{PI}	749	786	1436	1506	1650	1922	ps	
	t _{PCOUT}	483	507	1000	1049	1149	1339	ps	
LVCMOS	t _{PI}	674	707	1223	1282	1405	1637	ps	
	t _{PCOUT}	408	428	787	825	904	1054	ps	
SSTL-2 Class I	t _{PI}	507	530	818	857	939	1094	ps	
	t _{PCOUT}	241	251	382	400	438	511	ps	
SSTL-2 Class II	t _{PI}	507	530	818	857	939	1094	ps	
	t _{PCOUT}	241	251	382	400	438	511	ps	
SSTL-18 Class I	t _{PI}	543	569	898	941	1031	1201	ps	
	t _{PCOUT}	277	290	462	484	530	618	ps	
SSTL-18 Class II	t _{PI}	543	569	898	941	1031	1201	ps	
	t _{PCOUT}	277	290	462	484	530	618	ps	
1.5-V HSTL	t _{PI}	560	587	993	1041	1141	1329	ps	
Class I	t _{PCOUT}	294	308	557	584	640	746	ps	

			Minimu	m Timing	-3	-3	-4	-5	
I/O Standard	Drive Strength	Parameter	Industrial	Commercial	Speed Grade (3)	Speed Grade (4)	Speed Grade	Speed Grade	Unit
Differential	8 mA	t _{OP}	913	957	1715	1799	1971	2041	ps
SSTL-2 Class I		t _{DIP}	933	979	1781	1869	2047	2131	ps
	12 mA	t _{OP}	896	940	1672	1754	1921	1991	ps
		t _{DIP}	916	962	1738	1824	1997	2081	ps
Differential	16 mA	t _{OP}	876	918	1609	1688	1849	1918	ps
SSTL-2 Class II		t _{DIP}	896	940	1675	1758	1925	2008	ps
	20 mA	t _{OP}	877	919	1598	1676	1836	1905	ps
		t _{DIP}	897	941	1664	1746	1912	1995	ps
	24 mA	t _{OP}	872	915	1596	1674	1834	1903	ps
		t _{DIP}	892	937	1662	1744	1910	1993	ps
Differential	4 mA	t _{OP}	909	953	1690	1773	1942	2012	ps
SSTL-18 Class I		t _{DIP}	929	975	1756	1843	2018	2102	ps
0.000	6 mA	t _{OP}	914	958	1656	1737	1903	1973	ps
		t _{DIP}	934	980	1722	1807	1979	2063	ps
	8 mA	t _{OP}	894	937	1640	1721	1885	1954	ps
		t _{DIP}	914	959	1706	1791	1961	2044	ps
	10 mA	t _{OP}	898	942	1638	1718	1882	1952	ps
		t _{DIP}	918	964	1704	1788	1958	2042	ps
	12 mA	t _{OP}	891	936	1626	1706	1869	1938	ps
		t _{DIP}	911	958	1692	1776	1945	2028	ps
Differential	8 mA	t _{OP}	883	925	1597	1675	1835	1904	ps
SSTL-18 Class II		t _{DIP}	903	947	1663	1745	1911	1994	ps
J.200 II	16 mA	t _{OP}	894	937	1578	1655	1813	1882	ps
		t _{DIP}	914	959	1644	1725	1889	1972	ps
	18 mA	t _{OP}	890	933	1585	1663	1821	1890	ps
		t _{DIP}	910	955	1651	1733	1897	1980	ps
	20 mA	t _{OP}	890	933	1583	1661	1819	1888	ps
		t _{DIP}	910	955	1649	1731	1895	1978	ps

Table 5–76. St	ratix II I/O	Output Delay	for Row Pins	(Part 3 of 3)					
			Minimu	m Timing	-3	-3	-4	-5	
I/O Standard	Drive Strength	Parameter	Industrial	Commercial	Speed Grade (2)	Speed Grade (3)	Speed Grade	Speed Grade	Unit
1.8-V HSTL	4 mA	t _{OP}	972	1019	1610	1689	1850	1956	ps
Class I		t _{DIP}	930	976	1555	1632	1787	1883	ps
	6 mA	t _{OP}	975	1022	1580	1658	1816	1920	ps
		t _{DIP}	933	979	1525	1601	1753	1847	ps
	8 mA	t _{OP}	958	1004	1576	1653	1811	1916	ps
		t _{DIP}	916	961	1521	1596	1748	1843	ps
	10 mA	t _{OP}	962	1008	1567	1644	1801	1905	ps
		t _{DIP}	920	965	1512	1587	1738	1832	ps
	12 mA	t _{OP}	953	999	1566	1643	1800	1904	ps
	(1)	t _{DIP}	911	956	1511	1586	1737	1831	ps
1.5-V HSTL	4 mA	t _{OP}	970	1018	1591	1669	1828	1933	ps
Class I		t _{DIP}	928	975	1536	1612	1765	1860	ps
	6 mA	t _{OP}	974	1021	1579	1657	1815	1919	ps
		t _{DIP}	932	978	1524	1600	1752	1846	ps
	8 mA (1)	t _{OP}	960	1006	1572	1649	1807	1911	ps
		t _{DIP}	918	963	1517	1592	1744	1838	ps
LVDS		t _{OP}	1018	1067	1723	1808	1980	2089	ps
		t _{DIP}	976	1024	1668	1751	1917	2016	ps
HyperTransport		t _{OP}	1005	1053	1723	1808	1980	2089	ps
		t _{DIP}	963	1010	1668	1751	1917	2016	ps

Notes to Table 5-76:

- (1) This is the default setting in the Quartus II software.
- (2) These numbers apply to -3 speed grade EP2S15, EP2S30, EP2S60, and EP2S90 devices.
- (3) These numbers apply to -3 speed grade EP2S130 and EP2S180 devices.

Maximum Input & Output Clock Toggle Rate

Maximum clock toggle rate is defined as the maximum frequency achievable for a clock type signal at an I/O pin. The I/O pin can be a regular I/O pin or a dedicated clock I/O pin.

However, when the output is a double data rate input/output (DDIO) signal, both edges of the input clock signal (positive and negative) trigger output transitions (Figure 5–9). Therefore, any distortion on the input clock and the input clock buffer affect the output DCD.

CIK INPUT OUTPUT Output

OUTPUT Output

OUTPUT Output

Inst8 Inst8 OUTPUT OUTPUT OUTPUT

Figure 5–9. DCD Measurement Technique for DDIO (Double-Data Rate) Outputs

When an FPGA PLL generates the internal clock, the PLL output clocks the IOE block. As the PLL only monitors the positive edge of the reference clock input and internally re-creates the output clock signal, any DCD present on the reference clock is filtered out. Therefore, the DCD for a DDIO output with PLL in the clock path is better than the DCD for a DDIO output without PLL in the clock path.

Tables 5–80 through 5–87 give the maximum DCD in absolution derivation for different I/O standards on Stratix II devices. Examples are also provided that show how to calculate DCD as a percentage.

Row I/O Output	Maximum DCD for Non-DDIO Output							
Standard	-3 Devices	Unit						
3.3-V LVTTTL	245	275	ps					
3.3-V LVCMOS	125	155	ps					
2.5 V	105	135	ps					

PLL Timing Specifications

Tables 5–92 and 5–93 describe the Stratix II PLL specifications when operating in both the commercial junction temperature range (0 to 85 $^{\circ}$ C) and the industrial junction temperature range (–40 to 100 $^{\circ}$ C).

Name	Description	Min	Тур	Max	Unit
f _{IN}	Input clock frequency	2		500	MHz
f _{INPFD}	Input frequency to the PFD	2		420	MHz
f _{INDUTY}	Input clock duty cycle	40		60	%
f _{EINDUTY}	External feedback input clock duty cycle	40		60	%
t _{injitter}	Input or external feedback clock input jitter tolerance in terms of period jitter. Bandwidth ≤ 0.85 MHz		0.5		ns (p-p)
	Input or external feedback clock input jitter tolerance in terms of period jitter. Bandwidth > 0.85 MHz		1.0		ns (p-p)
toutjitter	Dedicated clock output period jitter			250 ps for ≥ 100 MHz outclk 25 mUl for < 100 MHz outclk	ps or mUI (p-p)
t _{FCOMP}	External feedback compensation time			10	ns
f _{OUT}	Output frequency for internal global or regional clock	1.5 (2)		550.0	MHz
toutduty	Duty cycle for external clock output (when set to 50%).	45	50	55	%
f _{SCANCLK}	Scanclk frequency			100	MHz
t _{CONFIGPLL}	Time required to reconfigure scan chains for enhanced PLLs		174/f _{SCANCLK}		ns
f _{OUT_EXT}	PLL external clock output frequency	1.5 (2)		550.0 (1)	MHz

Table 5–97. DQS Phase Jitter Specifications for DLL-Delayed Clock (tDQS PHASE_JITTER) Note (1)						
Number of DQS Delay Buffer Stages (2)	DQS Phase Jitter	Unit				
1	30	ps				
2	60	ps				
3	90	ps				
4	120	ps				

Notes to Table 5–97:

- (1) Peak-to-peak phase jitter on the phase shifted DDS clock (digital jitter is caused by DLL tracking).
- (2) Delay stages used for requested DQS phase shift are reported in your project's Compilation Report in the Quartus II software.

Table 5–98. DQS Phase-Shift Error Specifications for DLL-Delayed Clock (tDQS_PSERR) (1)								
Number of DQS Delay Buffer Stages (2)	-3 Speed Grade	-4 Speed Grade	–5 Speed Grade	Unit				
1	25	30	35	ps				
2	50	60	70	ps				
3	75	90	105	ps				
4	100	120	140	ps				

Notes to Table 5–98:

- (1) This error specification is the absolute maximum and minimum error. For example, skew on three delay buffer stages in a C3 speed grade is 75 ps or \pm 37.5 ps.
- (2) Delay stages used for requested DQS phase shift are reported in your project's Compilation Report in the Quartus II software.

Table 5–99. DQS Bus Clock Skew Adder Specifications (tDQS_CLOCK_SKEW_ADDER)					
Mode	DQS Clock Skew Adder	Unit			
×4 DQ per DQS	40	ps			
×9 DQ per DQS	70	ps			
×18 DQ per DQS	75	ps			
×36 DQ per DQS	95	ps			

Note to Table 5-99:

(1) This skew specification is the absolute maximum and minimum skew. For example, skew on a $\times 4$ DQ group is 40 ps or ± 20 ps.